Revision Record					
Control No.	**Revision**	**Description**	**Date**	**Drawn**	**Approved**

TDG HOLDING CO., LTD.

R : A0
C N .:

TMAX-1770-XXX-M M lded P e I d c

Features

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Applications

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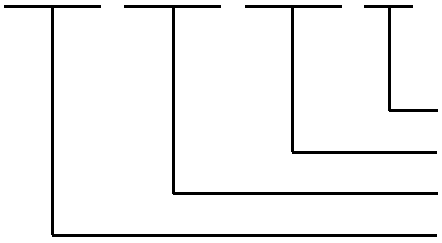
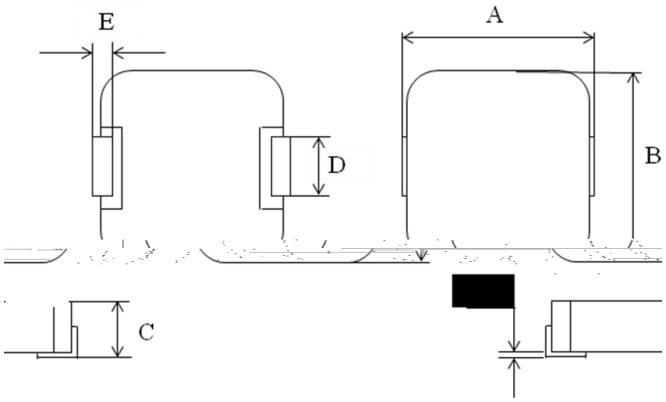
Product Description

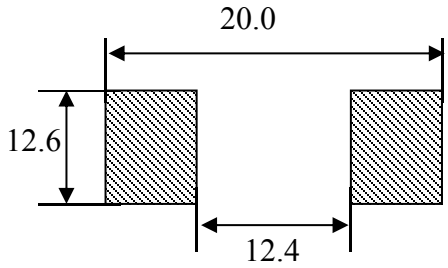


Dimensions



	17.5 Max.
	17.15 Max.
	7.0 Max.
	11.8±0.3
	2.5±0.5
	0~0.30

Recommend Land Pattern Dimensions



Marking

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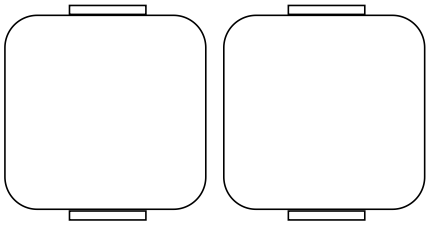

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Notes:

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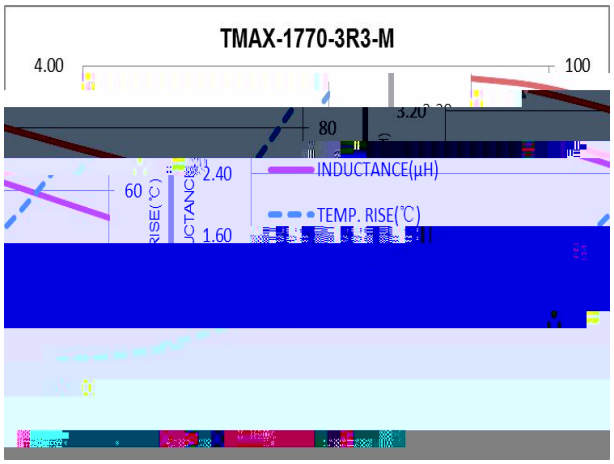
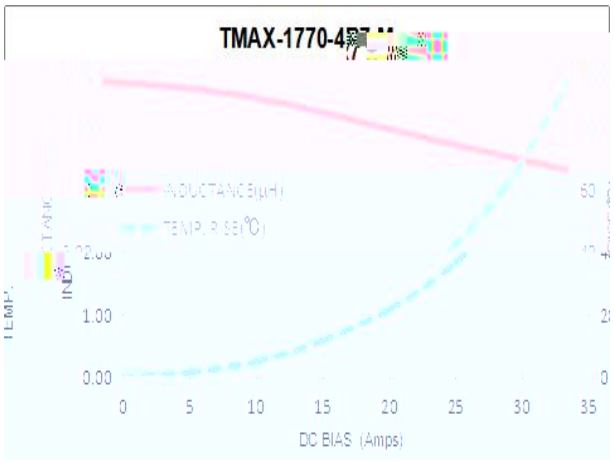
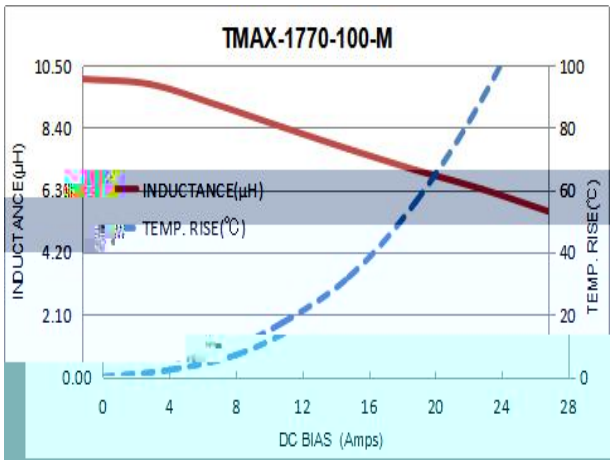
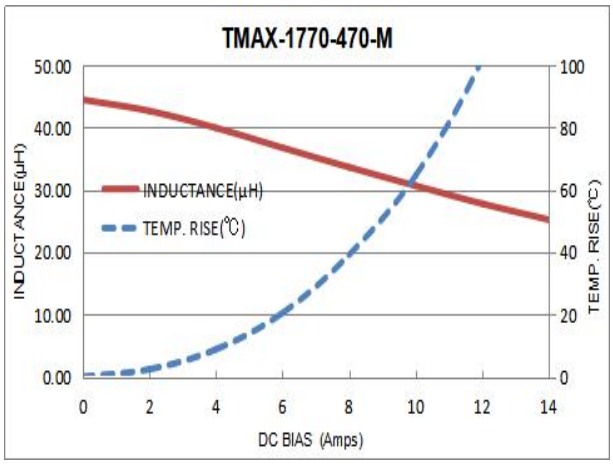
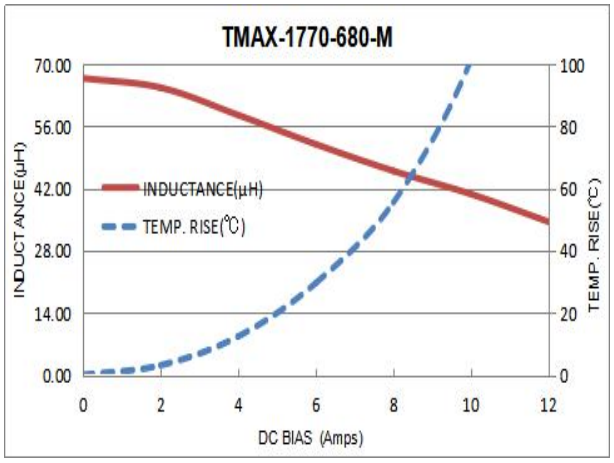
Inductance and Temperature Rise vs. DC Current











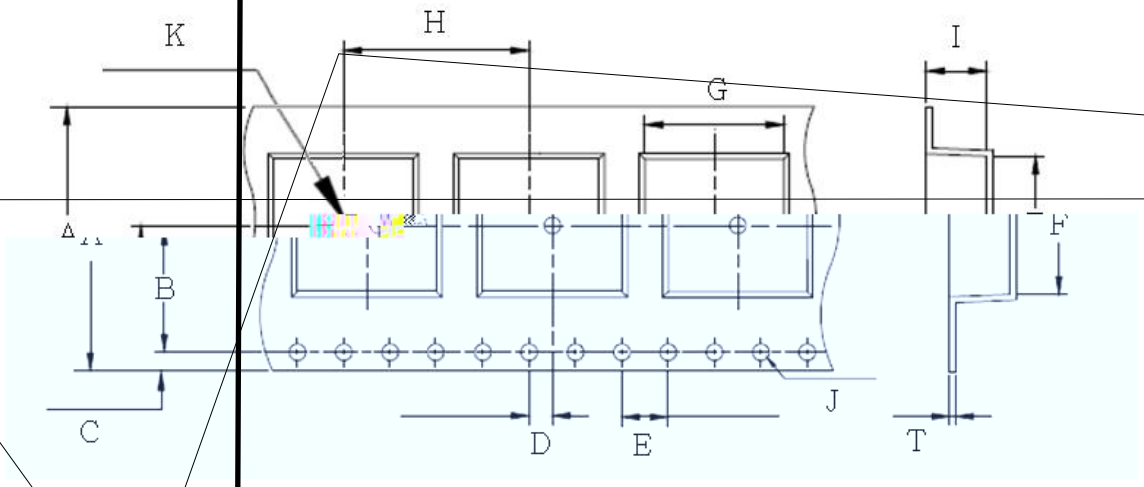
Reliability:

Item	Test Method	Specification and Requirement
	± ± ℃ ±	
		±

Reliability:

Item	Test Method	Specification and Requirement
	± ± → → ± ± →	±
	±	
	±	
	±	
	±	

Packaging Dimensions



±	±	±	±	±	±
±	±	±	±	±	±

[redacted]

±	±	

Peeling of top cover tape

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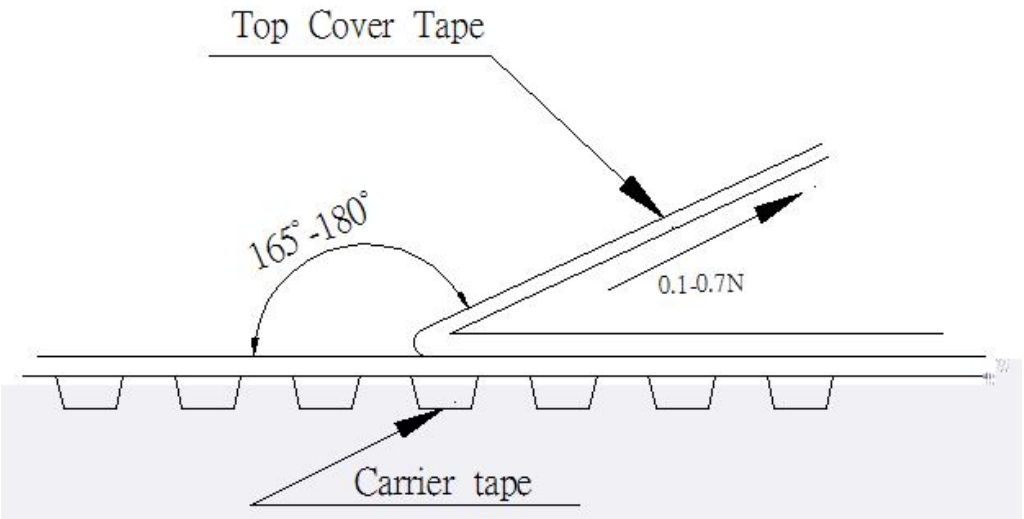

Reflow Profile

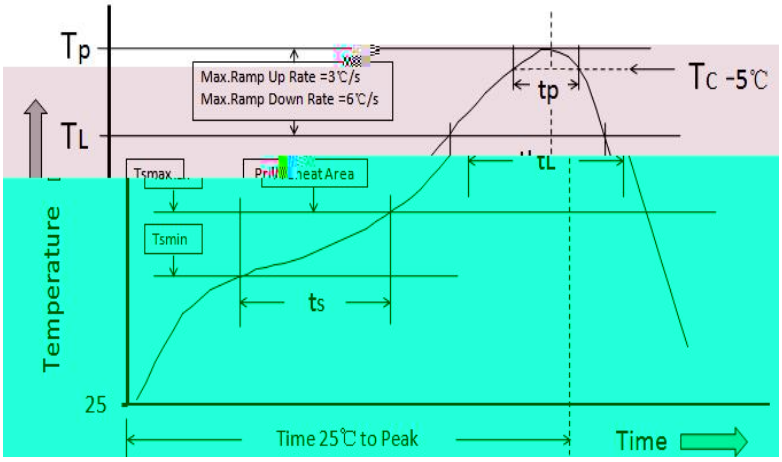

Table1-StandardSnPb Solder(Tc)

Package Thickness	Volume mm³ <350	Volume mm³ ≧350
<	℃	℃
≧	℃	℃

Table2-Lead(Pb)Free Solder(Tc)

Package Thickness	Volume mm³ <350	Volume mm³ 350-2000	Volume mm³ >2000
<	℃	℃	℃
	℃	℃	℃
	℃	℃	℃

Reference JDEC J-STD-020(latest revision)

Profile Feature		Standard SnPb solder	Lead(Pb) Free Solder
		℃	℃
		℃	℃
		℃	℃
		℃	℃
℃			
		℃	℃
℃			

Numbers of taping

●

Label marking

●

●

Production Label

✓

✓

✓

✓

✓

Shipping Label

✓

✓

✓

✓

✓

Care note for use

➢ **Storage Condition**

➢ **Use Temperature**

✓

➢ **Model**

✓

✓

Care note for Safety

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